DELL E2222H Teardown Instruction

S4

S5

S6

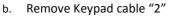
- 1. Remove Rear Cover Screw and Stand Screws
- a. Remove screws "1~6" on rear cover with electric screwdriver
- b. Torque: 12.0 +/- 0.5Kgf/cm, Phillips screwdriver



- 2. Remove Rear Cover
- Pry off the back cover of the machine with the aid of the dismantling fixture, in the sequence of "Bottom->Left/Right->Top"



- b. Remove Light Bar and Keypad Cable:
- a. Remove acetate cloth tape marked with "1", then remove light bar (grasp on Pin then pull outwards to remove)
 b. Demove Kenned cable "2"

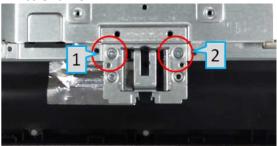




- 4. Remove VGA screw
- a. Remove screws "1~2" with electric screwdriver
- b. Torque: 12.0 +/- 0.5Kgf/cm, hex screwdriver



- 5. Remove Chassis Screw
- a. Remove screws "1~2" with electric screwdriver
- b. Torque: 3.5 +/- 0.5Kgf/cm, Phillips screwdriver



- 6. Remove Aluminium Foil and LVDS Cable
- a. Remove aluminium tape then remove LVDS cable (Pinch on clips on the sides)





S1

S2

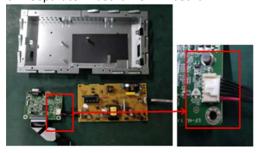
S3

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- 7. Remove PCBA 1
- a. Remove mylar (squared in red in the upper picture)
- Remove grounding screw "1" then locking screws marked "2~5" with electric screwdriver
- c. Torque: 5.5 +/- 0.5Kgf/cm, Phillips screwdriver



- 8. Remove PCBA 2
- a. Remove PI board and IF board
- b. Separate PI board from IF board



- 9. Remove LVDS Cable and Light Bara
 - Remove light bar from PI board (grasp on Pin then pull upwards to remove) Remove LVDS cable from IF board (lift



10.

S10

a. Remove keypad from front cover (loosen hook circled in red first)

Remove Keypad



S11

S12

- Remove Components on PI Board 1
 Remove electrolyte capacitor >25mm height (squared in red) from printed circuit boards
- b. Cut the glue between bulk cap and PCBA with knife – ensure cutting path within the glue, don't touch bulk cap and PCBA



- 12. Remove Components on PI Board 2
- a. Take out the capacitor pin solder with soldering iron
- b. Lift the bulk capacitor away from power board



S7

S8

S9

a.

b.

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1. Product Material Information

The following substances, preparation, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/422/EEC.

Capacitors / Condensers (containing PCB/PCT)	Not used
Mercury containing components	Not used
Batteries	Not used
Printed circuit boards (with surface greater than 10 square cm)	Product has printed circuit boards (with surface greater than 10 square cm)
Component contain toner, ink and liquids	Not used
Plastic containing BFR	
Component and waste contain asbestos	Not used
CRT	Not used
Component contain CFC, HCFC, HGC and HC	Not used
Gas discharge lamps	Not use
LCD display > 100 cm2	Product LCD greater than 100cm2
External electric cable	Product has external cables
Component contain refractory ceramic fibers	Not used
Component contains radio-active substances	Not used
Electrolyte capacitors (height > 25mm, diameter >25mm)	Product has electrolyte capacitors (height > 25mm)

2. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver (Philip head with Φ5 mm & Φ3 mm)
- Screwdriver (Hexagonal to remove VGA connectivity)
- Soldering iron
- Knife